



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  *: Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2013-11-04
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Antonella Lanzafame	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	EB6R*VA18AAJ	A	ZY1A	2013-11-04
Amount	UoM	Unit type	ST ECOPACK Grade	
54.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	5.0,4.4,1.0	14	flat	
Comment	TSSOP 14 BODY 4.4 PITCH 0.65; MD valid for CP: TSZ124IPT.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-20th June 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	EB6R*VA18AAJ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other inorganic materials	0.783	mg	supplier	Silicon Die	Silicon (Si)	7440-21-3		0.739	mg	943806	13685
Silicon Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	11494	167
Silicon Die				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	2554	37
Silicon Die				supplier	metallization	Titanium Nitride (TiN)	25583-20-4		0.002	mg	2554	37
Silicon Die				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	1277	19
Silicon Die				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.003	mg	3831	56
Silicon Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.018	mg	22989	333
Silicon Die				supplier	passivation	Gamma-butyrolactone	96-48-0		0.006	mg	7663	111
Silicon Die				supplier	passivation	Polyhydroxyamide	55295-98-2		0.003	mg	3831	56
LEADFRAME	Copper and its alloy	21.142	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		20.298	mg	960079	375889
LEADFRAME				supplier	ALLOY	Iron (Fe)	7439-89-6		0.5	mg	23650	9259
LEADFRAME				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.028	mg	1324	519
LEADFRAME				supplier	ALLOY	Phosphorus (P)	7723-14-0		0.008	mg	378	148
LEADFRAME				supplier	ALLOY	Silver (Ag)	7440-22-4		0.308	mg	14568	5704
DIE ATTACH	other organic materials	2.438	mg	supplier	GLUE	Epoxy Resin A	9003-36-5		0.171	mg	70139	3167
DIE ATTACH				supplier	GLUE	Epoxy Resin B	68475-94-5		0.098	mg	40197	1815
DIE ATTACH				supplier	GLUE	Silver (Ag)	7440-22-4		1.875	mg	769073	34722
DIE ATTACH				supplier	GLUE	Lactone	96-48-0		0.098	mg	40197	1815
DIE ATTACH				supplier	GLUE	Polyoxypropylenediamine	9046-10-0		0.098	mg	40197	1815
DIE ATTACH				supplier	GLUE	2,6-Diglycidyl phenyl allyl ether oligomer	Trade Secret		0.098	mg	40197	1815
BONDING WIRE	Other inorganic materials	0.286	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		0.286	mg	1000000	5296
ENCAPSULATION	other organic materials	28.008	mg	supplier	MOLDING COMPOUND	Epoxy Resin	Trade secret		2.52	mg	89974	46667
ENCAPSULATION				supplier	MOLDING COMPOUND	Silica Fused	60676-86-0		23.528	mg	840046	435704
ENCAPSULATION				supplier	MOLDING COMPOUND	Phenol Resin	Trade Secret		1.82	mg	64981	33704
ENCAPSULATION				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		0.14	mg	4999	2593
FINISHING	Other inorganic materials	1.343	mg	supplier	CONNECTION COATING	Tin (Sn)	7440-31-5		1.343	mg	1000000	24870